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ICs for Consumer Electronics

DDC-PLUS-Deflection Controller SDA 9362

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SDA 9362 Revision His	story:	Current Version: 1998-02-01					
Previous Version:		1997-04-01					
PagePage(in previous(in currentVersion)Version)		Subjects (major changes since last revision)					
30	32	Nom./max. average current and max. standby current specified					
30	32	Specification of charge current pump of PLL pin LF is unnecessary					

Data Classification

Maximum Ratings

Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

Recommended Operating Conditions

Under this conditions the functions given in the circuit description are fulfilled. Nominal conditions specify mean values expected over the production spread and are the proposed values for interface and application. If not stated otherwise, nominal values will apply at T_A =25°C and the nominal supply voltage.

Characteristics

The listed characteristics are ensured over the operating range of the integrated circuit.

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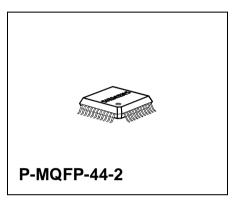
DDC-PLUS-Deflection Controller

1 Overview

1.1 Features

- Deflection Protection 16:9 / 4:3
- I²C Bus alignment of all deflection parameters
- All EW-, V- and H-functions (incl. Φ 2)
- PW EHT compensation
- PH EHT compensation
- Compensation of H-phase deviation (e.g. caused by white bar)
- Upper/lower EW-corner correction separately adjustable
- V-angle correction: Vertical frequent linear modulation of H-phase
- V-bow correction: Vertical frequent parabolic modulation of H-phase
- Three reduced V-scan modes (75 %, 66 %, 50 % V-size) selectable
- H- and V-blanking time adjustable
- Partial overscan adjustable to hide the cut off control measuring lines in the reduced scan modes
- Stop/start of vertical deflection adjustable to fill out the 16/9 screen with different letterbox formats without annoying overscan
- Dynamic PH EHT-compensation (white bar)
- Self adaptation of V-frequency/number of lines per field between 192 and 680 for each possible line frequency
- Protection against EHT run away (X-rays protection)
- Protection against missing V-deflection (CRT-protection)
- Two digital outputs for general purpose, controlled by I²C Bus
- Selectable softstart of the H-output stage
- P-MQFP-44-2 package
- 5 V supply voltage

Туре	Ordering Code	Package
SDA 9362	Q67101-H5173-A701	P-MQFP-44-2



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1.2 General Description

The SDA 9362 is a highly integrated deflection controller for CTV receivers with doubled line and standard or doubled field frequencies. It controls among others an horizontal driver circuit for a flyback line output stage, a DC coupled vertical sawtooth output stage and an East-West raster correction circuit. All adjustable output parameters are I²C Bus controlled. Inputs are HSYNC, VSYNC and the line locked clock CLL.

1.3 Pin Configuration

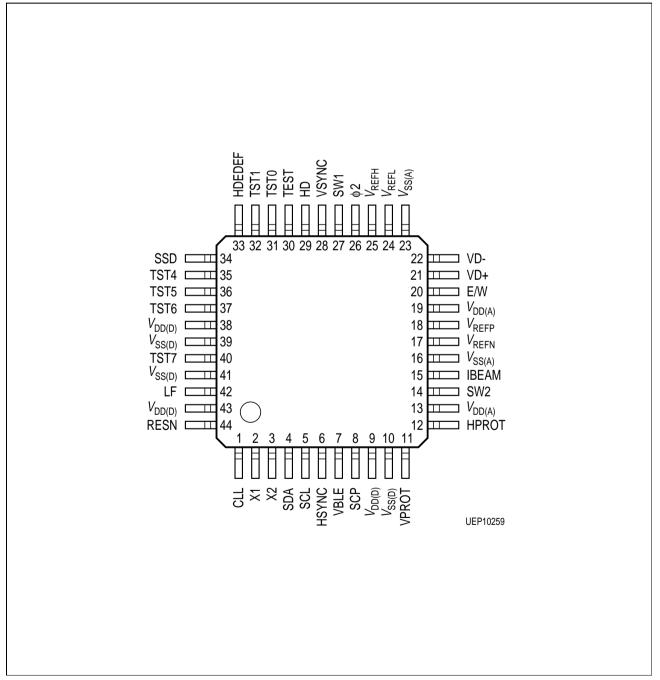


Figure 1

1.4 Pin Description

Pin No.	Symbol	Туре	Description
1	CLL	I/TTL	Clock input
2	X1	I	Reference oscillator input, crystal
3	X2	Q	Reference oscillator output, crystal
4	SDA	IQ	I ² C-Bus data
5	SCL	I	I ² C-Bus clock
6	HSYNC	I/TTL	H-sync input
7	VBLE	Q/TTL	Vertical blanking output
8	SCP	Q	Blanking signal with H- and color burst component (V-component selectable by I ² C Bus)
9	$V_{\rm DD(D)}$	S	Digital supply
10	$V_{\rm SS(D)}$	S	Digital ground
11	VPROT	I	Watching external V-output stage (input is the V-sawtooth from feedback resistor)
12	HPROT	I	Watching EHT (input is e.g. H-flyback)
13	$V_{DD(A)}$	S	Analog supply
14	SW2	Q/TTL	Output of an I ² C Bus controlled switch (Register 00 _H , Bit D5)
15	IBEAM	I	Input for a beam current dependent signal for stabilization of width, height and H-phase
16	$V_{\rm SS(A)}$	S	Analog ground
17	V_{REFN}	IQ	Ground for V_{REFP} , V_{REFH} , V_{REFL}
18	V _{REFP}	IQ	Reference voltage for IBEAM ADC, HPROT / VPROT thresholds
19	$V_{DD(A)}$	S	Analog supply
20	E/W	Q	Control signal output for East-West raster correction
21	VD+	Q	Control signal output for DC coupled V-output stage
22	VD-	Q	Like VD+
23	$V_{\rm SS(A)}$	S	Analog ground
24	V_{REFL}	IQ	Reference voltages for E/W-DAC, V-DAC
25	V_{REFH}	IQ	Like V _{REFL}
26	Ф2		Line flyback for H-delay compensation

1.4 Pin Description (cont'd)

Pin No.	Symbol	Туре	Description
27	SW1	Q/TTL	Output of an I ² C Bus controlled switch (Register 00 _H , Bit D3)
28	VSYNC	I/TTL	V-sync input
29	HD	Q	Control signal output for H driver stage
30	TEST	I/TTL	Switching normal operation (TEST = L) and test mode (TEST = H: pin 34 is an additional test pin)
31	TST0	I	Test pin, to be grounded
32	TST1	I	Test pin, to be grounded
33	HDEDEF	I/TTL	Defines the default value of HDE
34	SSD	I/TTL	Disables soft start (H)
35	TST4	I	Test pin, to be grounded
36	TST5	0	Test pin, don't connect
37	TST6	0	Test pin, don't connect
38	$V_{\rm DD(D)}$	S	Digital supply
39	$V_{\rm SS(D)}$	S	Digital ground
40	TST7	0	Test pin, don't connect
41	$V_{\rm SS(D)}$	S	Digital ground
42	LF	IQ	PLL loop filter
43	$V_{\rm DD(D)}$	S	Digital supply
44	RESN	I/TTL	Reset input, active low

1.5 Block Diagram

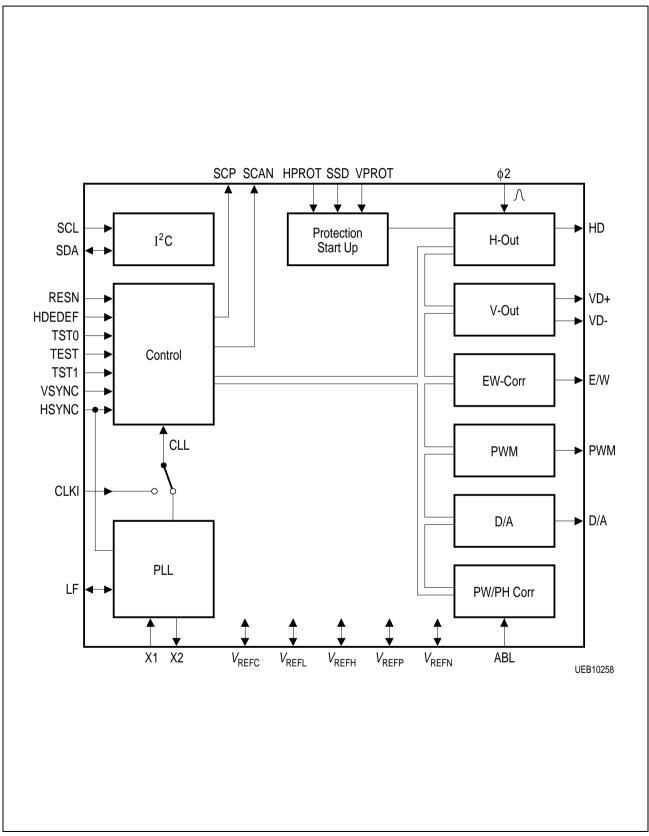


Figure 2

2 System Description

2.1 Functional Description

The main input signals are HSYNC with doubled horizontal frequency, VSYNC with vertical frequencies of 50/100 Hz or 60/120 Hz and the line locked clock CLL.

The output signals control the horizontal as well as the vertical deflection stages and the East-West raster correction circuit.

The H-output signal HD compensates the delays of the line output stage and its phase can be modulated vertical frequent to remove horizontal distortions of vertical raster lines (V-Bow, V-Angle). Time reference is the middle of the front and back edge of the line flyback pulse. A positive HD pulse switches off the line output transistor. Maximal H-shift is 2.25 μ s.

Picture tubes with 4:3 or 16:9 aspect ratio can be used by adapting the raster to the aspect ratio of the source signal.

The V-output sawtooth signals VD- and VD+ controls a DC coupled output stage and can be disabled. Suitable blanking signals are delivered by the IC.

The East-West output signal E/W is a vertical frequent parabola of 4th order, enabling an additional corner correction, separately for the upper and lower part.

Two I²C Bus controlled digital outputs are available for general purpose.

The picture width and picture height compensation (PW/PH Comp) processes the beam current dependent input signal IBEAM with effect to the outputs E/W and VD to keep width and height constant and independent of brightness.

The alignment parameter Horizontal Shift Compensation enables to adjust the influence of the input signal IBEAM on the horizontal phase.

The selectable start up circuit controls the energy supply of the H-output stage during the receiver's run up time by smooth decreasing the line output transistors switching frequency down to the normal operating value (softstart). HD starts with about 55 kHz and converges within 85 ms to its final value. The high time is kept constant. The normal operating pulse ratio H/L is 45/55. A watch dog function limits the period of the HD output signal independent of the clock CLL to max 35.2 μ s.

The protection circuit watches an EHT reference and the sawtooth of the vertical output stage. H-output stage is switched off if the EHT succeeds a defined threshold or if the V-deflection fails (**refer to page 36**). The function of this circuit is based on the internal quartz oscillator and therefore independent of the input clock CLL.

HPROT:	Input	$V_{\rm i}$ < V2	Continues blanking
		$V_{\rm i}$ > V1	HD disabled
		$V2 \le V_i < V1$	Operating range

VPROT: Vertical sawtooth voltage $V_i < V1$ in first half of V-period or $V_i > V2$ in second half: HD disabled

The pin SCP delivers the composite blanking signal SCP. It contains burst (V_b), H-blanking HBL (V_{HBL}) and selectable V-blanking (control bit SSC). The phase of the H-blanking period can be varied by I²C Bus. For the timing following settings are possible:

BD = 1BD = 0, BSE = 0 (default value) BD = 0, BSE = 1(alignment range) : $t_{BL} = 0$: $t_{HBL} = t_f$ (H-flyback time) : $t_{HBL} = (4 * H-blanking-time + 1) / CLL$: $t_{DBL} = (H-shift + 4 * H-blanking-phase -2 * H-blanking-time + 43) / CLL$: $t_{BL} = t_{VBL}$ during V-blanking period : t_{BL} is always t_{HBI}



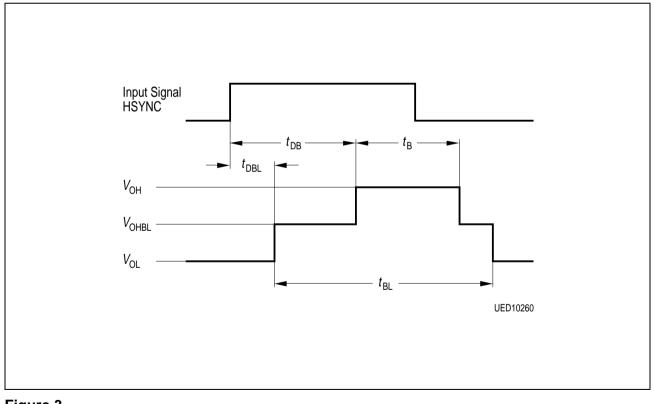


Figure 3

BG-pulse width t_{B}	54 / CLL
Delay to HSYNC t _{DB}	36 / CLL

2.2 Circuit Description

The system clock for the SDA 9362 has to be generated externally (e.g. in the SDA 9206) and applied to pin CLL. Its frequency must be always the line frequency (defined by the horizontal time reference HSYNC) multiplied by 864. If no HSYNC signal is available an internal horizontal synchronisation signal is derived from CLL (CLL divided by 879).

The input signal at VSYNC is the vertical time reference. It has to pass a window avoiding too short or long V-periods in the case of distorted or missing VSYNC pulses. The window allows a VSYNC pulse only after a minimum number of lines from its predecessor and sets an artificial one after a maximum number of lines. The window size is programmable by I²C Bus.

The beam current dependent input signal IBEAM is A/D converted and then digitally processed. The A/D Converter requires a clock frequency twice the frequency of CLL which is generated by an internal analog PLL with an external loop filter at pin LF.

Values which influence shape and amplitude of the output signals are transmitted as reduced binary values to the SDA 9362 via I²C Bus. A CPU which is designed for speed reasons in a pipe line structure calculates in consideration of feedback signals (e.g. IBEAM) values which exactly represent the output signals. These values control after D/A conversion the external deflection and raster correction circuits. The CPU firmware is stored in an internal ROM.

2.3 Reset Modes

The circuit is only completely reset at power-on/off (**timing diagram refer 5.3**). If the pin RESN has L-level or during standby operation some parts of the circuit are not affected (**timing diagram refer 5.4**):

	Power-On-Reset	External Reset (pin RESN=0)	Standby Mode (I ² C-Bit STDBY=1)
HD output	High	Active	Active
H-protection	Inactive	Active	Active
V-protection	Inactive	Active ¹⁾	Active ¹⁾
I ² C Interface (SDA, SCL)	Tristate	Ready	Ready
I ² C Register 01 _H 1B _H	Set to default values	Set to default values	Set to default values
I ² C Register 00 _H , 48 _H	Set to default values	Not affected	Not affected
Status bit PONRES	Set to 1 ²⁾	Set to 1	Not affected
V _{REFP}	Not affected	Not affected	Not affected
V_{REFH}, V_{REFL}	Not affected	Not affected	Inactive
CPU	Inactive	Inactive	Inactive

¹⁾ Inactive if HPROT < V2 (typ. 2.4 V)

²⁾ Can only be read after Power-On-Reset is finished

Note: Power-On-Reset state is deactivated after ca. 32 cycles of the X1/X2 oscillator clock. RESN = Low and standby state are deactivated after ca. 42 cycles of the CLL clock.

2.4 Frequency Ranges

Н	V	n _L
31.25 kHz	50 Hz 100 Hz	625 NI / 1250l 625 l
31.5 kHz	60 Hz 120 Hz	525 NI / 1050 I 525 I

The allowed deviation of all input line frequencies is max. ±4.5 %.

n_L: Number of lines per frame

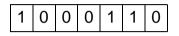
I: Interlaced

NI: Non interlaced

If NSA = 0 (subaddress $01_{\rm H}/\rm{D5}_{\rm H}$) number of lines per field is selfadaptable between 192 and 680 for each specified H-frequency.

2.5 I²C-Bus Control

2.5.1 I²C-Bus Address



2.5.2 I²C-Bus Format

write:

S 1 0 0 0 1 1 0 0 A	Subaddress	А	Data Byte	А	****	А	Ρ
read:							
S 1 0 0 0 1 1 0 1 A	Status byte	А	Data Byte n	A	****	NA	Ρ

Reading starts at the last write address n. Specification of a subaddress in reading mode is not possible.

- S: Start condition
- A: Acknowledge
- P: Stop condition
- NA: Not acknowledge

An automatical address increment function is implemented.

After switching on the IC, all bits are set to defined states (00_H) (exception: HDE depends on pin 33; see page 17)

2.5.3 I²C-Bus Commands

Control Item	Sub- addr.	D7	D6	D5	D4	D3	D2	D1	D0	Allowed Range	Effective Range	Can be Disabled by Bit	Default Value if Disabled	Unit
Deflection control 0	00 _H			S	ee k	oelov	N			-	-	_	_	_
Deflection control 1	01 _H			s	ee k	belov	N			-	-	_	-	-
Vertical shift	02 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	_
Vertical size	03 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Vertical linearity	04 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Vertical S-correction	05 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Vertical EHT compensation ¹⁾	06 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	_
Horizontal size	07 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Pin phase	08 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	-
Pin amp	09 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Upper corner pin correction	0A _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	-
Lower corner pin correction	0B _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	_
Horizontal EHT compensation ¹⁾	0C _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	-	-	-
Horizontal shift	$0D_{H}$	B6	B5	B4	B3	B2	B1	B0	Х	-6463	-6463	_	_	1/CLL
Vertical angle	$0E_{H}$									-128127	-128127	_	_	_
Vertical bow	OF_H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	-128127	_	_	_
Vertical blanking time ¹⁾	10 _H		B6	B5	B4	B3	B2	B1	B0	0127	a)	BSE = 0	b)	lines
Horizontal blanking time	11 _H					B3			B0	063	063	BSE = 0	H-flyback	4/CLL
Horizontal blanking phase	12 _H								Х	-3231	-3231	_	_	4/CLL
Start vertical scan 1)	13 _H	B7	B6	B5	B4	B3	B2	B1	B0	-128127	c)	SSE = 0	9	line
Vertical scan width 0 ¹⁾	14 _H	Х	Х	Х	Х	Х	Х	B9	B8	03	d)	STE = 0	e)	256 lines
Vertical scan width 1 1)	15 _H	B7	B6	B5	B4	B3	B2	B1	B0	0255	d)	STE = 0	e)	lines
Guard band ¹⁾	16 _H	Х	Х	B5	B4	B3	B2	B1	B0	063	063	GBE = 0	3	half lines
Start reduced scan ¹⁾	17 _H	Х	Х	B5	B4	B3	B2	B1	B0	063	0, 263	SRSE = 0	2	line
Vertical sync control	18 _H			S	iee k	belov	N			1	_	_	_	-
MinNo. of lines / field 1)	19 _H	B7	B6	B5	B4	B3	B2	B1	B0	0255	0255	_	_	2 lines
Max. No. of lines / field 1)	$1A_{H}$	Β7	B6	B5	B4	B3	B2	B1	B0	0255	0255	_	_	2 lines
AFC EHT compensation ¹⁾	1B _H	B5	B4	B3	B2	B1	B0	Х	Х	-3231	-3231	_	_	_
Internal voltage Ref control	48 _H			S	ee b	belov	N			_	_	_	_	

¹⁾ see 2.5.5: Explanation of some control items

a) The effective range for Vertical Blanking Ti	me:
16 127 (absolute value)	if $STE = 0$
0 127 (offset value)	if STE = 1.
b) The "default value if disabled" for Vertical B	lanking Time:
21 (absolute value)	if $STE = 0$
8 (offset value)	if STE = 1.
c) The effective range for Start Vertical Scan:	
2 127 (absolute value)	if STE = 0
	if STE = 1 and NSA = 1

	if STE = 1	and I	NSA = 1
-128 127 (offset value) if STE = 1	and I	NSA = 0.

d) The effective range for Vertical Scan (total width: 10 Bit): 160 ... 684 lines.

e) The "default value if disabled" for **Vertical Scan** equals the number of lines of the source signal reduced by the control value for **Start Vertical Scan**. (E.g.: input signal: 262 lines per field; Start vertical scan = 8 lines; then (if SSE = 1, STE = 0) vertical scan = 262 - 8 = 254 lines.

At power on the RAM containing the control items is cleared. Therefore all data are zero by default before transferring individual values via I²C Bus.

Allowed values out of the effective range are limited, e. g. Vertical blanking time = 3 is limited to 16 if STE = 0 (that means a minimum of 16 lines is blanked).

There are five bits (SRSE, BSE, SSE, STE, GBE) in the deflection control byte 1 for disabling some control items. If one of these bits is "0", the value of the corresponding control item will be ignored and replaced by the value "default value if disabled" in the table above.

2.5.4 Detailed Description

The **Deflection Control Byte 0** includes the following bits:

VOFF	STDBY	SW2	BD	SW1	VR1	VR0	HDE
------	-------	-----	----	-----	-----	-----	-----

VOFF:

Vertical off

0: normal vertical output due to control items

1: vertical saw-tooth is switched off, vertical protection is disabled

STDBY: Stand-by mode

- 0: normal operation
- 1: stand-by mode (all internal clocks are disabled)

SW2:	Setting of output SW2 0: output SW2 has L-le 1: output SW2 has H-le	
BD:	Blanking disable 0: horizontal and vertic 1: horizontal and vertic	•
SW1:	Setting of output SW1 0: output SW1 has L-le 1: output SW1 has H-le	
VR1 VR0:		e (16:9 source on 16:9 display) (16:9 source on 4:3 display) (two 4:3 sources on 16:9 display) (two 16:9 sources on 16:9 display)
HDE:	HD enable 0: line is switched off (1: line is switched on (Default value depends of HDEDEF = Low: 0 HDEDEF = High: 1	,

The **Deflection Control Byte 1** includes the following bits:

X VDC NSA STE GBE SRSE SSE BSE

VDC:

Vertical dynamic compensation

- 0: influence of the beam current input IBEAM on the vertical sawtooth is static ('zooming' correction)
- 1: influence of the beam current input IBEAM on the vertical sawtooth is dynamic ('ripple' correction)

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NSA:	No self adaptation0: self adaptation on1: self adaptation off
STE:	Scan time enable0: control items for vertical scan width 0 and width 1 are disabled1: control items for vertical scan width 0 and width 1 are enabled
GBE:	Guard band enable0: control item for guard band is disabled1: control item for guard band is enabled
SRSE:	Start reduced scan enable0: control item for start reduced scan is disabled1: control item for start reduced scan is enabled
SSE:	Start scan enable0: control item for start vertical scan is disabled1: control item for start vertical scan is enabled
BSE:	Blanking select enable0: control items for blanking times are disabled1: control items for blanking times are enabled

The Vertical Sync Control Byte includes the following bits:

Х	VBLE	SSC	Х	NI	Х	Х	Х
VBLE:	(this bi trailing 0: ou	edge of VE tput VBLE	change the BLE is affeo has the sa	VBL comp cted) me timing a onger than V	as VBL com	ponent at	SCP
SSC:	0: ou	astle withou tput SCP w tput SCP w	vith VBL co	mponent . componer	nt		

NI: Non interlace

0: interlace depends on source

1: no interlace

The Internal Voltage Ref Control Byte includes the following bits:

BANDG5	BANDG4	BANDG3	BANDG2	BANDG1	BANDG0	BANDG	BANDG4
						OFF	OFF

BANDG5 ... Adjustment of internal bandgap reference BANDG0:100000: Reference Output voltage min : 011111: Reference Output voltage max

Typical adjustment range is 1 V.

BANDGOFF: Bandgap off

- 0: V_{REFH} , V_{REFL} derived internally from V_{REFP}
- 1: external references on V_{REFP} , V_{REFH} , V_{REFL} have to be applied (in this case BANDG4OFF must be = 1)

BANDG4OFF: Bandgap 4 V off

- 0: internal bandgap reference is used for V_{REFP}
- 1: external reference on V_{REFP} (4 V) has to be applied

The Status Byte includes the following bits

HPON	VPON	_	_	_	_	_	PONRES
------	------	---	---	---	---	---	--------

HPON: H-protection on

- 0: normal operation of the line output stage
- 1: high level on input HPROT has switched off the line

VPON: V-protection on

- 0: normal operation of the vertical output stage
- 1: incorrect signal on input VPROT has switched off the line

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PONRES: Power On Reset
0: after bus master has read the status byte
1: after each detected reset
Note: PONRES is reset after this byte has been read.

2.5.5 Explanation of Some Control Items

Start Vertical Scan

If enabled (SSE = 1) this control item defines the start of calculation of the vertical sawtooth, the east/west parabola and the vertical function required for the vertical modulated output HD.

Vertical Scan (width0 and width1)

The total width of this control item is 10 Bit. Therefore two (width0 and width1) registers are necessary. If enabled (STE = 1) it defines the duration of the vertical scan. When the vertical period has more lines than the sum of **Start Vertical Scan** and **Vertical Scan**, the calculation of the vertical sawtooth, the east/west parabola and the vertical parabola required for HD stops so that the corresponding output signals remain unchanged till the next vertical synchron pulse.

Guard Band

This control item is useful for optimizing self adaptation. Video signals with different number of lines in consecutive fields (e. g. VCR search mode) must not start the procedure of self adaptation. But switching between different TV standards has to change the slope of the vertical sawtooth getting always the same amplitude (self adaptation).

To avoid problems with flicker free TV systems which have alternating number of lines per field an average value of four consecutive fields is calculated. If the deviation of these average values (e.g. PAL: 312.5 lines or 625 half lines) is less or equals **Guard Band**, no adaptation takes place. When it exceeds **Guard Band**, the vertical slope will be changed.

Start Reduced Scan

If enabled (SRSE = 1) this item defines the start of the D/A-conversion of the calculated vertical sawtooth. From begin of the vertical flyback to the line defined by **Start Reduced Scan** the output signals VD+, VD- remain unchanged (flyback level). Other outputs are not affected.

a) control bits VR1, VR0 # 00 (reduction of vertical size)

In this case the byte is useful for e.g. displaying 16/9 source format on 4/3 picture tubes without visible RGB lines generated of the automatic cut-off control (partial

overscan). It defines the start of the reduced amplitude (factors 0.5, 0.66, 0.75) of the vertical sawtooth (**refer page 35**). When **Start Reduced Scan** = 0 the reduction takes place over all lines including vertical flyback.

b) control bits VR1, VR0 = 00 (no reduction of vertical size)

If Start Reduced Scan > Start Vertical Scan the D/A conversion of the sawtooth starts (Start Reduced Scan - Start Vertical Scan) lines after begin of the calculation.

This causes a jump of the output voltage VD+, VD- from flyback to scan level. It may be useful to hide the automatic cut-off control lines if no overscan is desired (e.g. for VGA display). If **Start Reduced Scan** <= **Start Vertical Scan** this byte has no effect.

Vertical EHT Compensation

This item controls the influence of the beam current dependent input signal IBEAM on the outputs VD+ and VD- according to the following equation

 $\Delta V_{\text{VDPP}} = \Delta V_{\text{IBEAM}} * \frac{\text{Vertical EHT compensation} + 128}{512} * 0.57^{1)}$

 ΔV_{VDPP} : variation of VD+ and VD- peak-to-peak voltage

 ΔV_{IBEAM} : variation of IBEAM input voltage

¹⁾ the factor 0.57 depends on V_{REFP} , V_{REFH} , V_{REFL}

If **Vertical EHT Compensation** = -128 the outputs VD+ and VD- are independent of the input signal IBEAM.

Horizontal EHT Compensation

This item controls the influence of the input signal IBEAM on the output E/W according to the following equation:

 $\Delta V_{\rm EW} = \Delta V_{\rm IBEAM} * \frac{\text{Horizontal EHT compensation} + 128}{128} * 2,12^{1)}$

 $\begin{array}{ll} \Delta V_{\text{EW}}: & \text{variation of E/W output voltage} \\ \Delta V_{\text{IBEAM}}: & \text{variation of IBEAM input voltage} \\ & \stackrel{1)}{} \text{the factor 2.12 depends on } V_{\text{REFP}}, V_{\text{REFH}}, V_{\text{REFL}} \\ & \text{If Horizontal EHT Compensation} = -128 \text{ the output E/W is independent} \\ & \text{of the input signal IBEAM.} \end{array}$

AFC EHT Compensation

Deviation of the horizontal phase caused by high beam current (e.g. white bar) can be eliminated by this control item. The beam current dependent input signal IBEAM is multiplied by **AFC EHT Compensation**.

Additional to the control items Vertical angle, Vertical bow and Horizontal shift, this product influences the horizontal phase at the output HD according to the following equation:

$$\Delta \phi = \Delta V_{\text{IBEAM}} * \frac{\text{AFC EHT compensation}}{64} * \frac{52^{1)}}{\text{CLL}}$$

 $\Delta \phi$:variation of horizontal phase at the output HD
(positive values: shift left, negatives values: shift right) ΔV_{IBEAM} :variation of IBEAM input voltage (units: Volt)CLL:864 * f_{H}

 $^{1)}$ the factor 52 depends on V_{REFP}

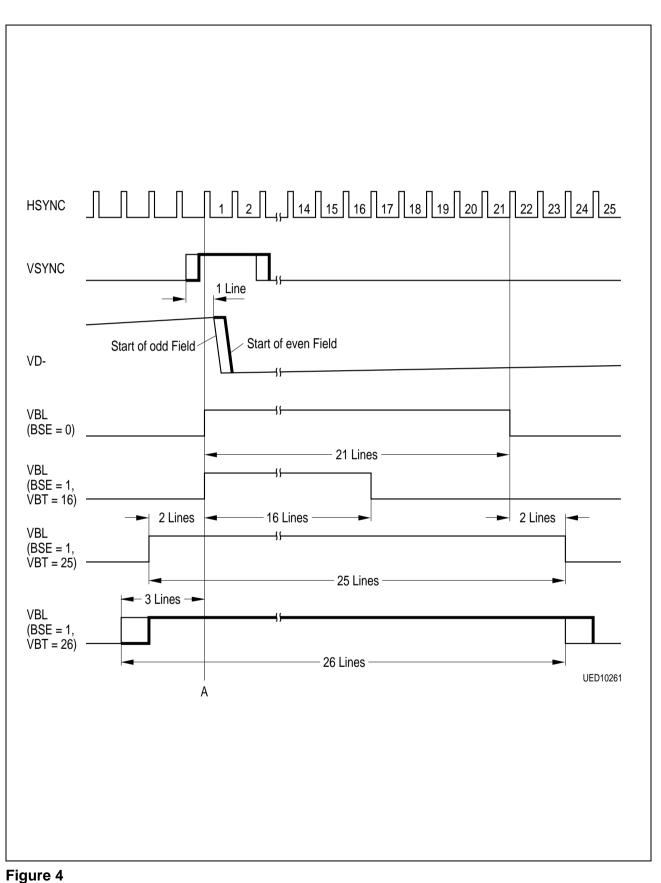
Vertical Blanking Time (VBT)

VBT defines the vertical blanking pulse VBL which is part of the output signal SCP. VBL is synchronized with the leading edge of HSYNC. It always starts and stops at the beginning of line and never in the center.

a) Case of STE = 0

In this case the control item Vertical blanking time defines the duration of the V-blanking pulse (VBL) exactly in number of lines. Because of IC internal limitations 16 through 127 lines can be blanked. If BSE = 0 the control item Vertical blanking time is disabled and always 21 lines (default value if disabled) are blank. After power on the control bit BSE is 0. Therefore 21 lines will be blanked before any programming of the IC. If **Vertical Blanking Time** is less or equals 21 lines, VBL starts (point A in fig. above) always 0 ... 0.5 line (new odd field) or 0.5 ... 1 line (new even field) prior to the vertical flyback. Otherwise VBL is concentric to a fictitious vertical flyback period of 21 lines, that means VBL starts (VBT - 21) / 2 lines at the end of an odd field or (VBT - 20) / 2 at the end of an even field prior to point A. Possible start points are only the beginning of line.

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Vertical Blanking Pulse VBL when STE = 0 and Number of Lines per Field = Constant

b) Case of STE = 1

In this case the control item Vertical blanking time is an extension for the V-blanking pulse.

- If BSE = 1 and VBT = 0 the V-blanking pulse has its minimum: it starts always at end of scan (line B in Fig. below) and ends at start of scan (line C) defined by the control items **Start Vertical Scan** (if SSE = 1) and **Vertical Scan**.

- BSE = 1 and (128 > VBT > 0) extend the V-blanking pulse according to the following

relationship

(If VBT > 127 this value is ignored and replaced by VBT - 128):

VBL starts VBT / 2 lines (even field) respectively (VBT + 1) / 2 lines (odd field) prior to line B.

VBL ends (VBT + 1) / 2 lines (even field) respectively VBT / 2 lines (odd field) after end of line C.

Possible start points are only the beginning of line.

- If BSE = 0 (after power on) the control item **Vertical Blanking Time** is disabled and VBL starts 4 lines prior to end of scan (line B) and ends 4 lines after start of scan (line C).

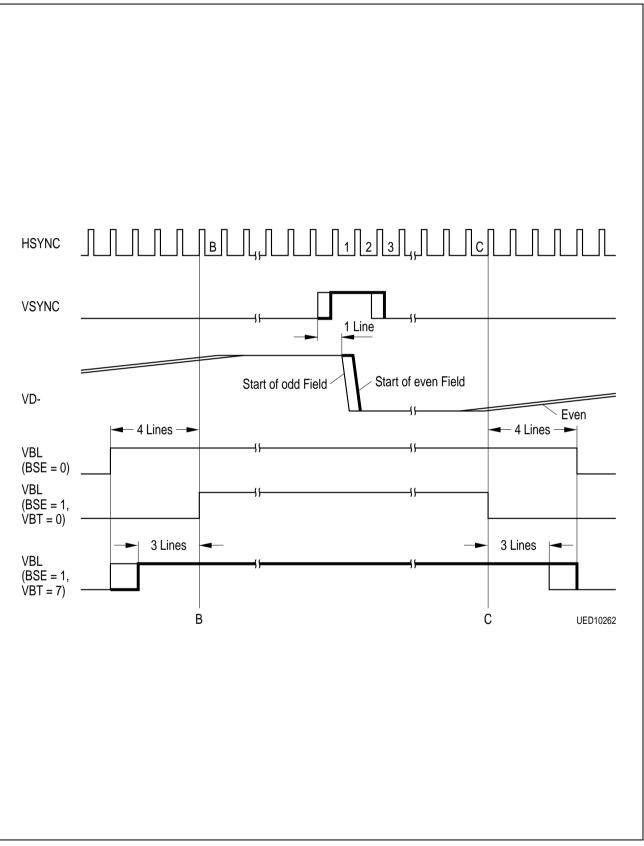


Figure 5 Vertical blanking pulse VBL when STE = 1

Minimum Number of Lines per Field

It defines the minimum number of lines per field for the vertical synchronisation. If the TV standard at the inputs VSYNC and HSYNC has less lines per field than defined by **Minimum Number of Lines per Field** no synchronisation is possible. The relationship between **Minimum Number of Lines per Field** and the minimum number of lines is given in the following table:

Minimum Number of Lines per Field	Minimum Number of Lines per Field
0	192
1	194
127	446
128	448
254	700
255	702

Maximum Number of Lines per Field

It defines the maximum number of lines per field for the vertical synchronisation. If the TV standard at the inputs VSYNC and HSYNC has more lines per field than defined by **Maximum Number of Lines per Field** no synchronisation is possible. The relationship between **Maximum Number of Lines per Field** and the maximum number of lines is given in the following table:

702
102
192
194
444
446
700

Most Important V-Deflection Modes for 4:3 CRT

Mode	Description	Characteristics	Notes	VR1 VR0	NSA	SRSE	GBE	STE	SSE
NO	Normal mode (for 4:3 source, Letterbox) with default settings	Self adaptation scan start = line 9 start of V-ramp = line 9 scan time: depends on source signal guard band = 1.5 lines	Mode after power on	00	0	0	0	0	0
N1	Normal mode (for 4:3 source, Letterbox) with user defined values	Self adaptation scan start = Start Vertical Scan if (Start Reduced Scan>Start Vertical Scan) start of V-ramp = Start Reduced Scan else start of V-ramp = Start Vertical Scan scan time: depends on source signal guard band = Guard Band/2 [lines]	Start of scan adjustable start of V-ramp adjustable guard band adjustable	00	0	1	1	0	1
SO	Shrink mode 75% (for 16:9 source) with default settings	Self adaptation scan start = line 9 start of reduced V-ramp = line 9 scan time: depends on source signal guard band = 1.5 lines		01	0	0	0	0	0
S1	Shrink mode 75% (for 16:9 source) with user defined values	Self adaptation scan start = Start Vertical Scan if (Start Reduced Scan>Start Vertical Scan) start of reduced V-ramp = Start Reduced Scan else start of reduced V-ramp = Start Vertical Scan scan time: depends on source signal guard band = Guard Band/2 [lines]	Start of scan adjustable start of reduced V-ramp adjustable guard band adjustable	01	0	1	1	0	1

Most Important V-Deflection Modes for 16:9 CRT

Mode	Description	Characteristics	Notes	VR1 VR0	NSA	SRSE	GBE	STE	SSE
-	Normal mode (for 16:9 or 4:3 source) with default settings	Self adaptation scan start = line 9 start of V-ramp = line 9 scan time: depends on source signal guard band = 1.5 lines	Mode after power on	00	0	0	0	0	0
N1	Normal mode (for 16:9 or 4:3 source) with user defined values	Self adaptation scan start = Start Vertical Scan if (Start reduced scan > Start vertical scan) start of V-ramp = Start reduced scan else start of V-ramp = Start vertical scan scan time: depends on source signal guard band = Guard Band /2 [lines]	Start of scan adjustable start of V-ramp adjustable guard band adjustable	00	0	1	1	0	1
Z	Zoom mode (for 4:3 source, Letterbox)	Scan start = (number_of_lines - Vertical Scan)/2 +8 scan time = Vertical Scan	Vertical scan controls zoom factor	00	0	x	х	1	0
SC	Scroll mode (for 4:3 source, Letterbox)	Scan start = (number_of_lines - Vertical Scan)/2 +8 + Start vertical scan scan time = Vertical Scan	Like above; start vertical scan can be additionally used for adjustment of picture phase	00	0	X	x	1	1
Μ	Manual mode (for 4:3 source, Letterbox)	Scan start = Start Vertical Scan scan time = Vertical Scan	Scan start and scan time are separately adjustable	00	1	Х	х	1	x
S2	Shrink mode 66% (for two 4:3 sources) with default settings	Self adaptation scan start = line 9 start of reduced V-ramp = line 9 scan time: depends on source signal guard band =1.5 lines		10	0	0	0	0	0
S3	Shrink mode 50% (for two 16:9 sources) with default settings	Self adaptation scan start = line 9 start of reduced V-ramp = line 9 scan time: depends on source signal guard band = 1.5 lines		11	0	0	0	0	0

3 Absolute Maximum Ratings

Parameter	Symbol	Limit	Values	Unit	Remark	
		min.	max.			
Operating temperature	T _A	-20	70	°C		
Storage temperature	T _{stg}	-40	125	°C		
Junction temperature	Tj		125	°C		
Soldering temperature	Ts		260	°C		
Input voltage	V_{I}	V _{SS} - 0.3 V	V _{DD} + 0.3 V			
Output voltage	V_{Q}	V _{SS} - 0.3 V	V _{DD} + 0.3 V			
Supply voltages	V_{DD}	-0.3	6	V		
Supply total voltage differentials		-0.25	0.25	V	1)	
Total power dissipation	P _{tot}		0.85	W		
Latch-up protection		-100	100	mA	All inputs/outputs	

¹⁾ Between any internally non-connected supply pin of the same kind. All $V_{\text{DD}(\text{D})}$ - and $V_{\text{DD}(\text{A})}$ - Pins are connected internally by about 3 Ω The $V_{\text{SS}(\text{D})}$ - Pins are connected internally by about 3 Ω

Note: Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions or at any other condition beyond those indicated in the operational sections of this specification is not implied.

3.1 Recommended Operating Conditions

Parameter	Symbol	Limit Values			Unit	Remark
		min.	nom.	max.		
Supply voltages	V_{DD}	4.5	5	5.5	V	
Ambient temperature	T _A	-20	25	70	°C	For analog parameters 0°C
TTL Inputs: CLL, HS	YNC, VSY	NC, TE	ST, SSI	D, HDED	EF, RE	ESN
H-input voltage	V_{IH}	2.0		$V_{\rm DD}$	V	
L-input voltage	V_{IL}	0		0.8	V	
Input VPROT						-
Threshold V1		1.4	1.5	1.6	V	$V_{REFP} = 4 \text{ V}$
Threshold V2		0.9	1.0	1.1	V	$V_{REFP} = 4 \text{ V}$
Input HPROT		•	I	I		•
Threshold V1		3.9	4	4.1	V	$V_{REFP} = 4 \text{ V}$
Threshold V2		2.1	2.4	2.7	V	$V_{REFP} = 4 \text{ V}$
Input IBEAM						
L-input voltage	V_{IL}		2		V	$V_{REFP} = 4 \text{ V}$
Full range input voltage			3		V	$V_{REFP} = 4 \text{ V}$
Reference Voltage Inp	out Pins (li	nternal	Voltage	Ref Cor	trol By	rte Reg 48 _H = 000000
V_{REFP} input voltage	V _{VREFP}		4		V	
V_{REFH} input voltage	V _{VREFH}		2.5		V	
V_{REFL} input voltage	V _{VREFL}		1.2		V	
V_{REFN} input voltage	$V_{\sf VREFN}$		0		V	
Input 						
L-input voltage	V_{IL}	0		0.7	V	$V_{REFP} = 4 \text{ V}$
H-input voltage	V _{IH}	2.0		V_{DD}	V	$V_{REFP} = 4 \text{ V}$
Input HSYNC	-1		I			1
Pulse width high		100		20000	ns	
Setup time	t _{SU}	7			ns	
Hold time	t _H	6			ns	
Input capacitance	CI			10	pF	
			1	1		•

3.1 Recommended Operating Conditions (cont'd)

Parameter	Symbol	Limit Values			Unit	Remark	
		min.	nom.	max.			
Input VSYNC							
Pulse width high		100		100/ <i>f</i> _H	ns	NI = 0	
Pulse width high		1.5/ <i>f</i> _H		100/ <i>f</i> _H		NI = 1	
Input capacitance	C_{I}			10	pF		
Input CLL			•				
Input frequency	f_{I}	25	27	30	MHz		
Input capacitance	C_{I}			10	pF		
Quartz Oscillator Inp	out / Outpu	ut X1, X	2				
Crystal frequency			12		MHz	Fundamental crystal type	
Crystal resonant impedance				25	Ω		
External capacitance			27		pF	See application information	
I ² C Bus (All Values a	are Referre	ed to m	in.(V _{IH})	and ma	×.(V _{IL}))		
H-input voltage	V_{IH}	3		V_{DD}	V		
L-input voltage	V_{IL}	0		1.5	V		
SCL clock frequency	f _{scl}	0		400	kHz		
Rise times of SCL, SDA	t _R			0.3	μs	$f_{\rm SCL}$ = 400 kHz	
Fall times of SCL, SDA	t _F			0.3	μs		
Set-up time DATA	t _{SU;DA}	100			ns		
Hold time DATA	t _{HD;DA}	0			ns		
Load capacitance	CL			400	pF		

3.2 Characteristics (Assuming Recommended Operating Conditions)

Parameter	Symbol	Limit Values			Unit	Remark
		min.	nom.	max.		
Average supply current	I _{CC}		50	100	mA	
Standby supply current				25	mA	
Output Pins: VBLE	, SW1, SW2	2				
Output low level	V_{OL}			0.4	V	$I_{\rm O}$ = 1 mA
Output high level	V _{OH}	2.8			V	<i>I</i> _O = -1 mA
Input / Output SDA						
Output low level	V_{OL}			0.6	V	$I_{\rm O}$ = 6 mA
Output SCP						
Output low level	V _{OL}	0		1	V	<i>I</i> _O = 1 mA
Output HBL level	V _{OHBL}	V _{DD} / 2 -0.4 V	V _{DD} / 2	V _{DD} / 2 +0.4 V		<i>I</i> _O = 100 μA
Output high level	V _{OH}	4.0		$V_{\rm DD}$	V	<i>I</i> _O = -1 mA
DAC Output E/W		-				
DAC resolution			10		Bit	Linear range: 100 900
DAC output low			1.45		V	Input data = 100^{1}
DAC output high			3.48		V	Input data = 900^{1}
Load capacitance	C_{L}			30	pF	
Output load		20			kΩ	
Zero error		-2 %		2 %		DAC output voltage = 2.5 V ²⁾
Gain error		-5 %		5 %		2)
INL		-0.2 %		0.2 %		2)
DNL		-0.1 %		0.1 %		2)

¹⁾ $V_{\text{REFH}} = 2.5 \text{ V}, V_{\text{REFL}} = 1.2 \text{ V}$

²⁾ V_{REFH} = 2.5 V, V_{REFL} = 1.2 V, Input range = 100 ... 900

Parameter	Symbol	Limit Values			Unit	Remark
		min.	nom.	max.	-	
DAC Output VD+, VD	_	1				
DAC resolution			14		Bit	Linear range: 1500 15000
DAC output low (VD-)			1.44		V	Input data = 1500^{1}
DAC output high (VD-)			3.58		V	Input data = 15000^{1}
DAC output low (VD-) - (VD+)			-2.12		V	Input data = 1500^{1}
DAC output high (VD-) - (VD+)			2.16		V	Input data = 15000^{1}
Load capacitance	CL			30	pF	
Output load		20			kΩ	
Zero error		-1 %		1 %		$(VD-) - (VD+) = 0 V^{2}$
Gain error		-5 %		5 %		2)
INL		-0.5 %		0.5 %		2)
DNL		Monoto	nous			Guar. by design

3.2 Characteristics (Assuming Recommended Operating Conditions) (cont'd)

¹⁾ $V_{\text{REFH}} = 2.5 \text{ V}, V_{\text{REFL}} = 1.2 \text{ V}$

²⁾ $V_{\text{REFH}} = 2.5 \text{ V}, V_{\text{REFL}} = 1.2 \text{ V}, \text{ Input range} = 1500 \dots 15000$

Reference Output V (Adjust. by Reg 48 _H ,		D2) (Re	g 48 _H , I	Bit D1 =	0, Bit [00 = 0)
Output voltage min				4.0	V	Bit D7 D2 = 100000
Output voltage max		4.0			V	Bit D7 D2 = 011111
Output current	IQ	-50		0	μA	
Reference Output V	REFH (Re	g 48 _H , Bi	t D1 = (0)		
Output voltage	V_{Q}	2.4	2.5	2.6	V	$V_{REFP} = 4 \text{ V}$
Reference Output V	REFL (Re	g 48 _H , Bi	t D1 = ()		
Output voltage	V_{Q}	1.1	1.2	1.3	V	$V_{REFP} = 4 \text{ V}$
Output HD						
Output low level	V_{OL}	0		1	V	<i>I</i> _O = 8 mA
Output high level	V _{OH}	V _{DD} -1 V		V_{DD}		<i>I</i> _O = -8 mA

4 Application Information

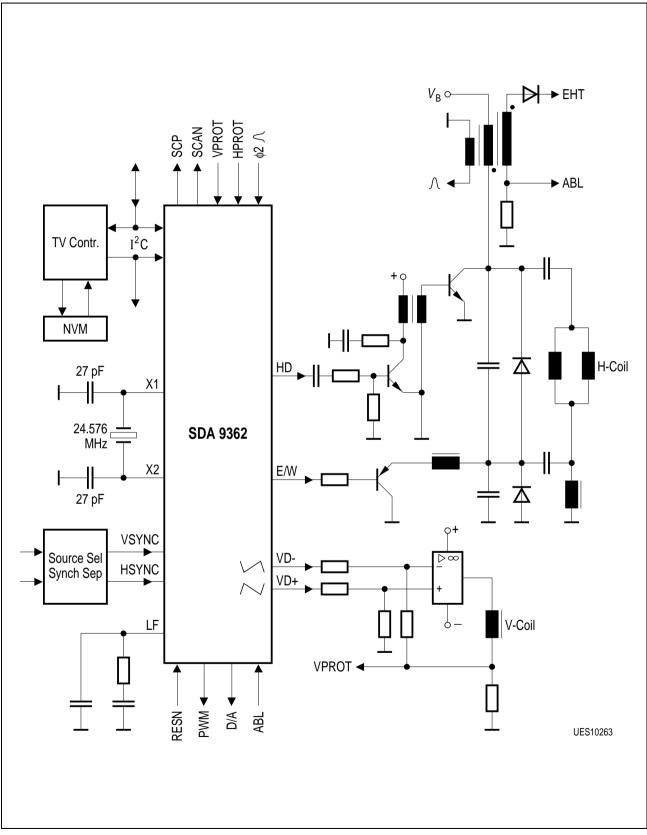


Figure 6

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5 Waveforms

5.1 VD- Output Voltage, 4/3-CRT and 16/9-Source

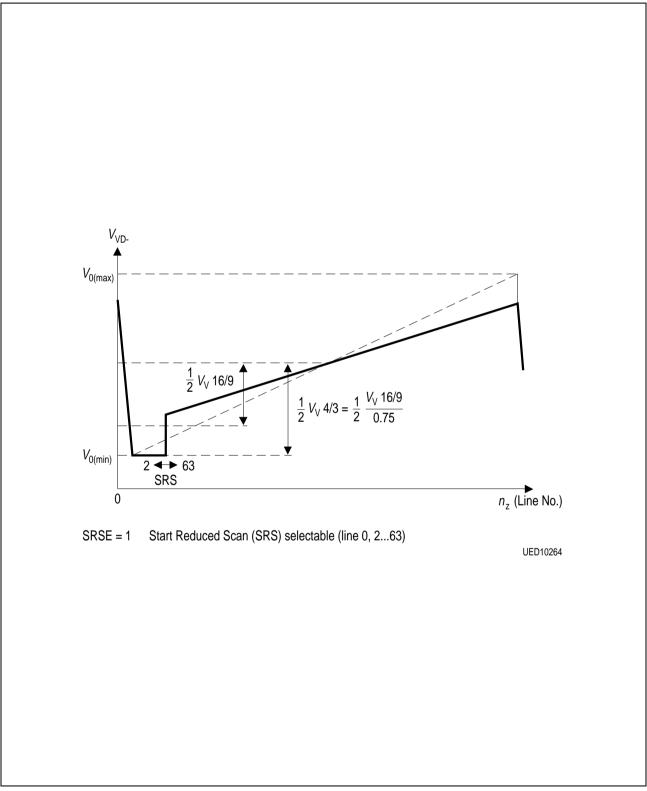


Figure 7

5.2 Function of H,V Protection

	HPROT	VPROT	Mode	SCP	HPON ²⁾ I ² C Bus	VPON ²⁾ I ² C Bus
1	V1 V2		Start up	Continuous blanking	0	0
2		V1	H, V operation	1)	0	0
3			EHT over- voltage	Continuous blanking after <i>t</i> 2	1 after t_2	0
4		$\begin{array}{c} + & + & + \\ - & - & - & - \\ - & - & - & - \\ - & - &$	H operation V short failure	Continuous blanking after t_0 if SSC = 0	0	0
5			V longer failure H off after <i>t</i> 1	Continuous blanking after t_0 if SSC = 0	0	1 after <i>t</i> 1
6			EHT short over- voltage	Continuous blanking after <i>t</i> 2	1 after t_2	1 after <i>t</i> 1

 $t_0 = 2 / f_v \dots 3 / f_v$ $t_1 = 64 / f_v \dots 128 / f_v$ $t_2 = 1 / f_v \dots 2 / f_v$

¹⁾ Depends on I²C-control items

²⁾ HPON or VPON = 1:HD = 0(OFF)

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5.3 Power On/Off Diagram

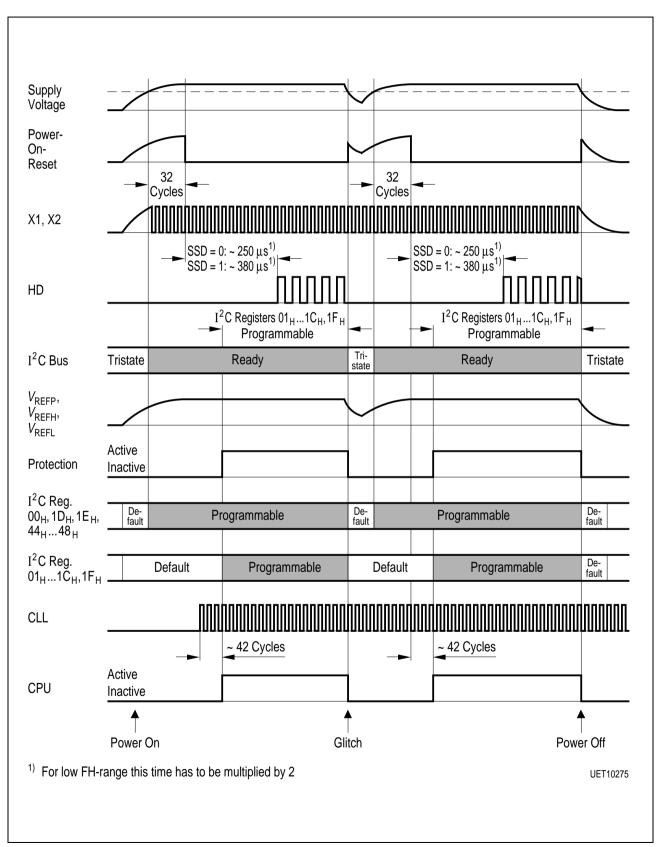


Figure 8

5.4 Standby Mode, RESN Diagram

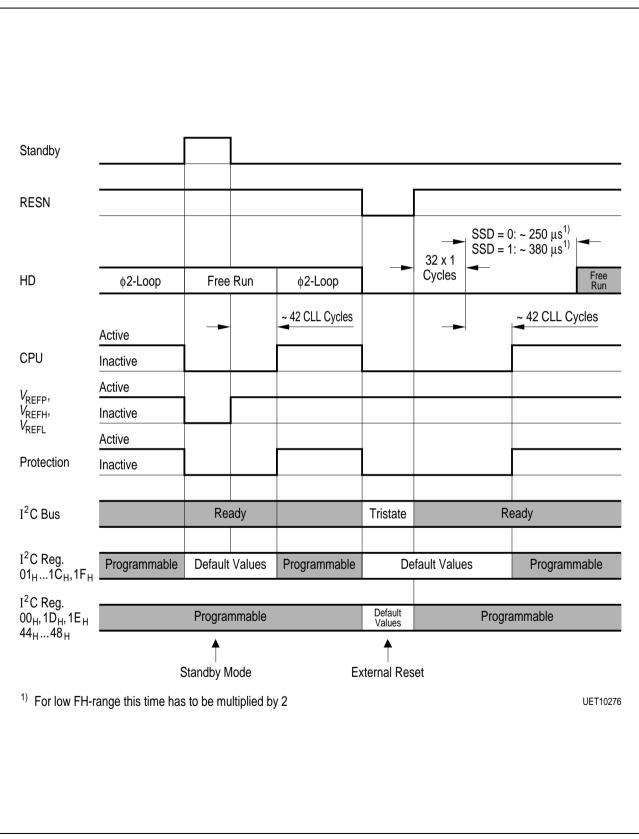
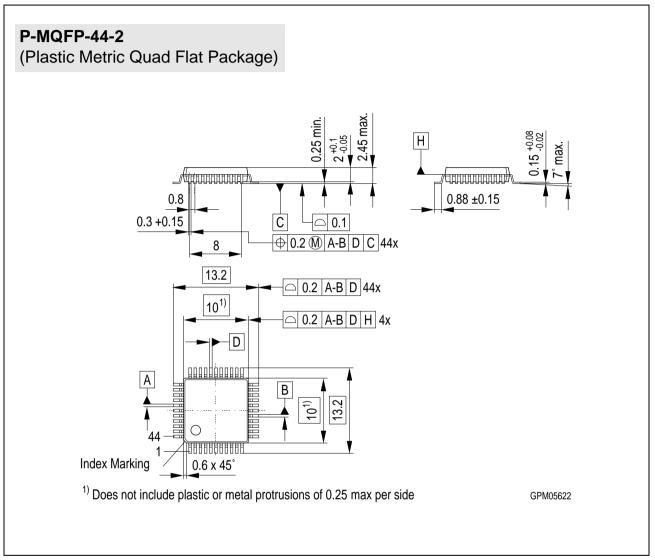


Figure 9

6 **Package Outlines**





Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information". SMD = Surface Mounted Device

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Dimensions in mm